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TABLE OF CONTENTS

SEMICONDUCTOR THERMAL MEASUREMENT AND MANAGEMENT SYMPOSIUM

Welcome to SEMI-THERM 35	iii
SEMI-THERM Committees	iv
SEMI-THERM Short Courses	v
SEMI-THERM Keynote Speaker: Tom Dolbear, AMD	ix
SEMI-THERM Luncheon Speakers: Domhnaill Hernon, Nokia; Paul Wesling, HP (retired)	x
SEMI-THERM Embedded Tutorial: George Meyer, Sobu Sun, Celsia; Pritish Parida, IBM	xii
SEMI-THERM Evening Tutorial: Lieven Vervecken, Diabatix	xiii
SEMI-THERM Teardown: Justin Dixon, Electronic Cooling Solutions, Inc.	xiv
Thermi Award: Dr. Peter Raad, Southern Methodist University.....	xv
Rosten Award: Jim VanGilder, Chris Healey, Wei Tian, Michael Condor, Quentin Menuisier	xvi
Thermal Hall of Fame Award: Márta Rencz, Budapest University of Technology and Economics.....	xvii

Session 1: LEDs

Chair: Jim Petroski, Mentor, A Siemens Business

A Methodology to Determine the Sites of Variability in an LED Assembly	1
Robin Bornoff ¹ , Thomas Mérelle ² , Josephine Sari ³ , Alessandro Di Bucchianico ³ , Gabor Farkas ¹ ¹ Mentor, A Siemens Business, ² Pi-Lighting, ³ Eindhoven University of Technology	
Accurate Thermal Transient Measurements Interpretation of Monochromatic LEDs	7
Alexeev Anton ¹ , Genevieve Martin ² , Grigory Onushkin ² , Jean-Paul Linnartz ² ¹ Eindhoven University of Technology, ² Signify	
Implementation of a Multi-domain LED Model and its Application for Optimized LED Luminaire Design	12
János Hegedüs ¹ , Gusztáv Hantos ¹ , Robin Bornoff ² , Márta Rencz ^{1,2} , András Poppe ^{1,2} ¹ Budapest University of Technology and Economics, ² Mentor, A Siemens Business	

Session 2: Two Phase Cooling

Chair: George Meyer and Sobo Sun, Celsia Inc.

Assessment of Critical Heat Flux on Finite Size Surfaces Under Pool Boiling	18
Julia Reed, Vijay K. Dhir, University of California, Los Angeles	
Molecular Dynamic Simulation of Evaporative Heat Transfer on Graphene Coated Silicon Substrate for Electronics Cooling	26
Binjian Ma ¹ , Rui Zhou ¹ , Shan Li ¹ , Junhui Li ¹ , Damena Agonafer ¹ , Baris Dogruoz ² , ¹ Washington University in St. Louis, ² Cisco Systems Inc.	
Experimental and Numerical Investigation of Microdroplets Evaporation on Porous Pillar Structures *	
Li Shan, Washington University in St. Louis	
Heat Pumps to Upgrade Data Center Waste Heat: Integration with 2-Phase Cooling *	
Steven Schon, QuantaCool	
Thermal Performance of Metal Foam Heat Sink with Pin Fins for Non-Uniform Heat Flux Electronics Cooling	30
Yongtong Li ^{1,2} , Liang Gong ¹ , Minghai Xu ¹ , Yogendra Joshi ² , ¹ China University of Petroleum, ² Georgia Institute of Technology	

* -- This presentation has no formal paper.

Session 3: Thermal Interface Materials

Chair: Jason Strader, Laird

Mechanical Cycling Reliability Testing of Thermal Interface Materials for Semiconductor Test 38

Dave Saums¹, Tim Jensen², Carol Gowans², Ron Hunadi², Mohamad Abo Ras³,
¹DS&A LLC, ²Indium Corporation, ³Berliner Nanotest und Design GmbH

Liquid Metal Innovations for High Performance TIMs *

Timothy Jensen, Indium Corporation

High Performance Lightweight Ceramic Material for Thermal Management in Electronic Devices 45

Bei Xiang, Chandra Raman and Xiang Liu, Momentive Performance Materials Quartz, Inc.

Performance of Durable High-Performance Polymer Composite TIMs Under Accelerated Aging Conditions 48

Hyungyung Jo, John A. Howarter, Purdue University

Thermal Diffusivity Characterization of Thick Graphite Foils *

Rick Beyerle, Martin Smalc, Rajath Kantharaj, Jonathan Taylor, Julian Norley, NeoGraf Solutions

Session 4: Automotive/Aerospace/Outdoor

Chair: Hussamedine Kabbani, Facebook

The Impact of Anodization on the Thermal Performance of Passively Cooled Electronic Enclosures Made of Die-cast Aluminum 51

Zhongchen Zhang¹, Michael Collins², Chris Botting³, Eric Lau³, Majid Bahrami¹,
¹Simon Fraser University, ²University of Waterloo, ³Delta-Q Technologies

Development of a 3D Printed Loop Heat Pipe 58

Bradley Richard, William G. Anderson, Joel Crawmer, Advanced Cooling Technologies Inc

Measurement of Thermal Resistance of Thermal Interface Materials with High In-plane Thermal Conductivity using Transient Thermal Based Structure Function Analysis *

Aloysius Davin Oetomo, Carbice Corporation

Session 5: CFD/Numerical Modeling

Chair: Taravat Khadivi, Qualcomm

Design using Multi-Scale, Multi-Physics Analyses And Shape Optimization, for Compact Heat Transfer Devices *

Daniel Bacellar, Dennis Nasuta, Cara Martin, Reinhard Radermacher, Optimized Thermal Systems, Inc.

Research on Package Thermal Resistance of Power Semiconductor Devices 61

Koji Nishi, Ashikaga University

The Necessity for Thermal-Electrical-Multiphysics for Board Heating in a Server Rack Unit *

Jared Harvest, Wade Smith, Satyajeet Padhi, ANSYS, Inc.

Temperature Profile of High Power Density (HPD) ASIC Device Mounted on Multi-layered Diamond Enhanced Heat Spreader *

Thomas Obeloer, Russell Mason, Daniel Twitchen and Firooz N. Faili, Element Six Technologies

Practical Evaluation of Thermally - Conductive Plastics and Guidelines for Use *

Dave Saums, DS&A LLC

Optimization of an Array of Heat Sinks to Satisfy an Arbitrary Objective Function *

Georgios Karamanis and Marc Hodes, Transport Phenomena Technologies, LLC

Session 6: Two Phase Cooling

Chair: Prithish Parida, IBM

CTE Matching Heat Pipe Thermal Ground Plane *

Nelson J. Gernert, Aavid Thermal Division of Boyd

* -- This presentation has no formal paper.

An Ultra-Thin Loop Heat Pipe with Long-Distance Heat Transport for Cooling of Small Electronic Devices	66
Shuto Tomita, Ai Ueno, Hosei Nagano, Nagoya University	
Evaluation of the Performance of Various Heat Pipe Mounting Methods with Various Thickness TIM's and Mounting Pressures *	
George A Meyer IV, Sobo Sun, Rock Chin, Celsia Inc	
Relative Performance of Two-Phase vs Solid Conductive Heat Spreaders for High Heat Flux Applications	70
Joe Boswell, Corey Wilson, Josh Schorp, and Dan Pounds, ThermAvant Technologies	
The Impact of Heat Rejection Architecture on the Thermal Performance of a Pumped Two-Phase Cooling System *	
Elizabeth Baker, Danah Valez, Timothy A. Shedd, Florida Polytechnic University	

Session 7: Consumer Electronics

Chair: Mark Carbone, Intel and Angel Han, Huawei

Analysis of Natural Frequency Dependency on Temperature Variation of MEMS Vibratory Gyroscope	76
Jacek Nazdrowicz, Andrzej Napieralski, Lodz University of Technology	
Battery Discharge Capacity Calculation by Temperature Measurement	83
Jeevan Kanesalingam and Khoo Li Lian, Motorola Solutions	
Exploring Heatpipe Configurations for Package On Package (PoP) Cooling	87
Sankarananda Basak ¹ , Ryota Watanabe ² , ¹ Intel Corp, ² Lenovo (Japan) Ltd.	

Session 8: Data Center Cooling

Chair: Marcelo del Valle, Intel

Simulation-Based Optimization of Data Center Cooling Performance using Performance Indicators	91
John Petrongolo ¹ , Kouros Nemati ² , and Kamran Fouladi ¹ , ¹ Widener University, ² Future Facilities	
Transient Analysis Overshoot in Temperature for High Power Thermal Solutions	96
Javier Avalos and Enrique Barreto, Intel Corp.	
Airflow Management using Active Air Dampers in Presence of a Dynamic Workload in Data Centers	101
Sadegh Khalili, Ghazal Mohsenian, Anuroop Desu, Kanad Ghose, Bahgat Sammakia, Binghamton University	

SUBMIT A PAPER FOR SEMI-THERM 36!

As you further develop a technique or application, consider documenting it for the thermal community. **SEMI-THERM 36** will begin accepting abstracts during the summer (deadline is September 15, 2019). We welcome your submissions! Visit us at www.semi-therm.org.

SEMI-THERM 36 is March 16-20, 2020 – *be there!*

* -- This presentation has no formal paper.